

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	("6722943").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:16
L2	2963189	wafer wafers substrate substrates semiconductor semiconductors	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:16
L3	4006071	(planarizing adj fluid) slurry etchant water	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:16
L4	151410	dispenser dispensers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:17
L5	2031392	slide slides sliding slidable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:17
L6	36	I2 same I3 same I4 same I5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:28
L7	113	(I2 same I3) and (I4 same I5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:21
L8	77	I7 not I6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:21

L9	112	I3 with I4 with I5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:23
L10	5	I9 and I2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:25
L11	107	I9 not I10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:25
L12	421455	(conditioner conditioning condition conditions) with (fluid slurry water)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:29
L13	0	I2 with I12 with I4 with I5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:29
L14	3	I2 same I12 same I4 same I5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:31
L15	8	(I2 same I12) and (I4 same I5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:32
L16	1119	(451/446).CCLS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:38

L17	568	(451/60).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 08:38
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	U	1	Document ID	Issue Date	Pages	Title
1		X	US 6398627 B1	20020604	8	Slurry dispenser having multiple adjustable nozzles
2		X	US 6284092 B1	20010904	8	CMP slurry atomization slurry dispense system
3		X	US 6280299 B1	20010828	17	Combined slurry dispenser and rinse arm
4		X	US 5997392 A	19991207	6	Slurry injection technique for chemical-mechanical polishing
5		X	US 5679063 A	19971021	10	Polishing apparatus
6		X	US 20020022440 A1	20020221	7	Supply of controlled amount of polishing slurry to semiconductor wafers
7		X	US 20020113039 A1	20020822	13	Integrated semiconductor substrate bevel cleaning apparatus and method

	Current OR	Current XRef	Retrieval Classif	Inventor	S	C	P	2	3
1	451/72	451/285; 451/41; 451/446; 451/447		Chiou; Wen-Chih et al.	X				
2	156/345.12	261/90; 451/446		Manfredi; Paul A.	X				
3	451/67	451/288; 451/446		Kennedy; Daniel et al.	X				
4	451/446	451/287		Chamberlin; Timothy S. et al.	X				
5	451/287	451/446; 451/60		Kimura; Norio et al.	X				
6	451/60	451/285; 451/286; 451/287; 451/288; 451/36; 451/41; 451/446		Kunugi, Takaharu	X				
7	216/92	134/1.3; 216/100; 216/105; 438/748; 438/754		Mok, Yeuk-Fai Edwin et al.	X				